



N-Channel SiC Power MOSFET

TO-247-3L (*Prefix :W)

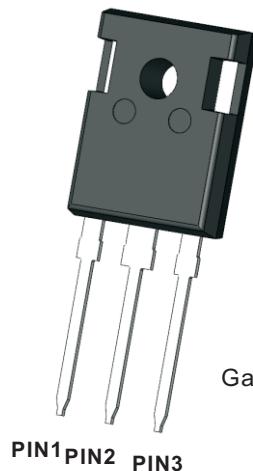
V_{DSS}	1200V
I_D@25°C	44.5A
R_{DS(on)}	60 mΩ

DESCRIPTION

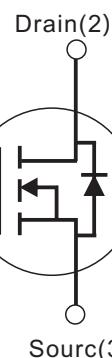
- 3rd Generation Sic Mosfet Technology
- High Blocking Voltage With Low On-resistance
- High-speed Switching With Low Capacitances
- Halogen Free, RoHS Compliant.

Features

- Reduce switching losses and minimize gate ringing
- Higher system efficiency
- Reduce cooling requirements
- Increase power density
- Increase system switching frequency



ROHS
COMPLIANT



SYMBOL

ABSOLUTE MAXIMUM RATINGS (TA=25°C, unless otherwise specified)

PARAMETER	Symbols	RATINGS	Test Conditions	Units
Drain-Source Voltage	V _{DSS}	1200	VGS=0V, ID=100μA	V
Gate-Source Voltage	V _{GS}	-15/+20	Absolute maximum values	V
Continuous Drain Current	I _D	44.5	VGS=18V, Tc=25°C	A
Continuous Drain Current	I _D	30.6	VGS=18V, Tc=110°C	A
Pulsed Drain Current (Note 1)	I _{D(Pulse)}	90.5	Pulse width tp limited by Tjmax	A
Power Dissipation	P _D	250	Tc=25°C	W
Operating junction and storage temperature	T _j , T _{stg}	-55 ~ +175		°C

Notes: 1. Repetitive Rating: Pulse width limited by maximum junction temperature.

Thermal Resistance

PARAMETER	Symbols	RATINGS	Units
Thermal resistance, junction – case.	R _{thJC}	0.6	°C/W
Thermal resistance, junction – ambient(min. footprint)	R _{thJA}	40	°C/W



ELECTRICAL CHARACTERISTICS (TA=25°C, unless otherwise specified)

PARAMETER	Symbols	TEST CONDITIONS	Min	Typ	Max	Units
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=100\mu A$	1200			V
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=1200V, V_{GS}=0V$			50	μA
		$V_{DS}=1200V, V_{GS}=0V, T_j=175^\circ C$			500	
Gate- Source Leakage Current	I_{GSS}	$V_{DS}=0V, V_{GS}=15V$			250	nA
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=0.25mA$	1.8	2.5	4.0	V
Static Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=20V, I_D=20A, T_j=25^\circ C$		60	80	$m\Omega$
		$V_{GS}=20V, I_D=20A, T_j=175^\circ C$		100		
DYNAMIC CHARACTERISTICS						
Input Capacitance	C_{iss}	$V_{GS}=0V, V_{DS}=800V$ $f=1MHz$ $V_{AC}=25mV$		2200		pF
Output Capacitance	C_{oss}			115		pF
Reverse Transfer Capacitance	C_{rss}			18.5		pF
Gate resistance	R_G	$f=1MHz, V_{AC}=25mV$		1.2		Ω
Transconductance $T_c=25^\circ C$	g_{fs}	$V_{DS}=12.5V, I_D=40A$		10.5		S
Turn-On Energy (Body Diode)	E_{ON}	$V_{DS}=800V, V_{GS}=-15/20V,$ $I_D=20A, L=80\mu H$		120		μJ
Turn-Off Energy (Body Diode)	E_{OFF}			44		μJ
Total Gate Charge (Note 1)	Q_G	$V_{DS}=800V$ $V_{GS}=-5V/20V$ $I_D=20A$		129		nC
Gate-Source Charge	Q_{GS}			29		nC
Gate-Drain Charge	Q_{GD}			64		nC
Turn-On Delay Time (Note 1)	$t_{D(ON)}$	$V_{DS}=800V, V_{GS}=-4/20V,$ $I_D=20A, R_G=2.7\Omega$ Timing relative to V_{DS}		25		ns
Turn-On Rise Time	t_R			24		ns
Turn-Off Delay Time	$t_{D(OFF)}$			20		ns
Turn-Off Fall Time	t_F			9		ns
DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS						
Maximum Body-Diode Continuous Current	I_S	$T_j=25^\circ C$			44.5	A
Drain-Source Diode Forward Voltage (Note 1)	V_{SD}	$I_{SD}=10A, V_{GS}=-4V$		5.8		V
Reverse Recovery Time (Note 1)	t_{rr}	$I_F=20A, V_{GS}=0V, di/dt$ $=300A/\mu s, VR=400V$		57		ns
Reverse Recovery Charge	Q_{rr}			109		μC

Notes:

1. Pulse Test: Pulse width $\leq 300\mu s$, Duty cycle $\leq 2\%$.



Typical Characteristics

Fig.1 Typical forward Output characteristics at $T_j=25^\circ\text{C}$

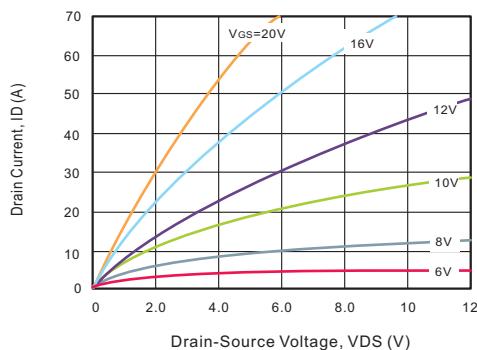


Fig.2 Typical forward Output characteristics at $T_j=175^\circ\text{C}$

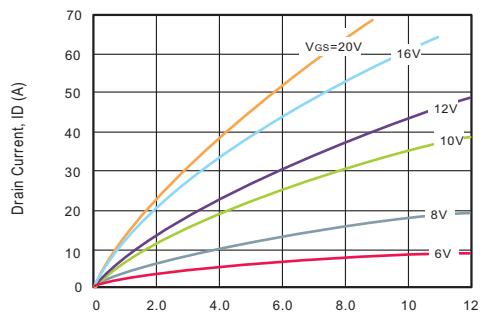


Fig.3 On-Resistance vs. Gate Voltage for various Temperature

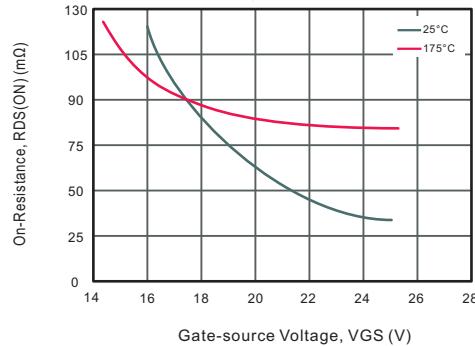


Fig.4 Threshold Voltage vs. Temperature

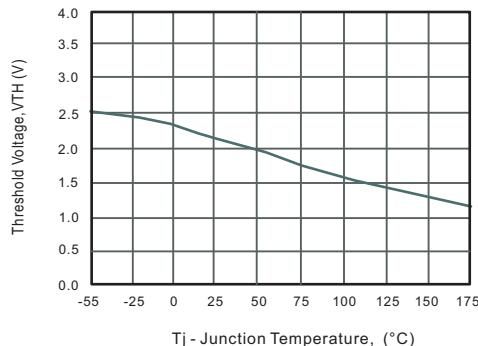


Fig.5 On-Resistance vs. Junction Temperature

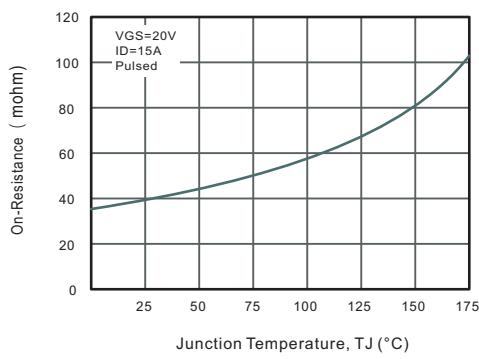


Fig.6 Diode Forward Voltage vs. Current

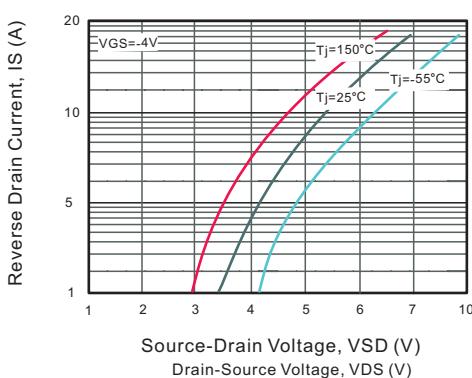


Fig.7 Capacitance Characteristics

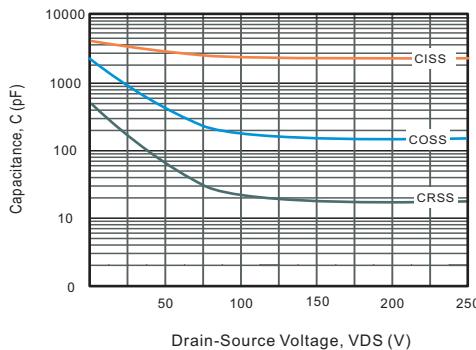
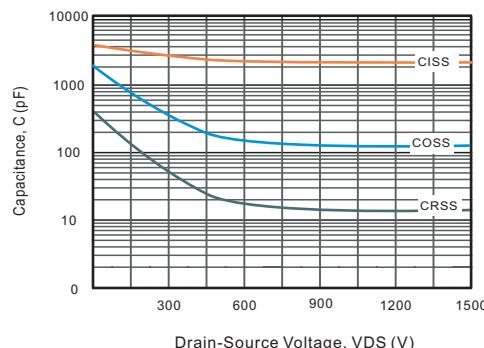


Fig.8 Capacitance Characteristics





Typical Characteristics

Fig.9 Safe Operating Area

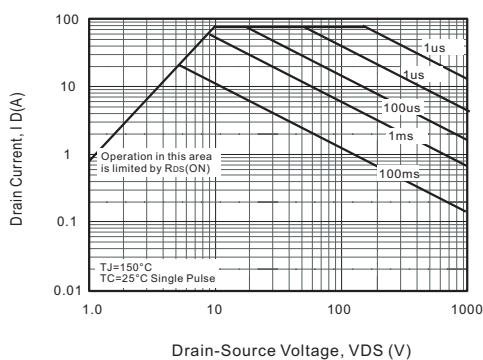


Fig.10 Drain Current Derating

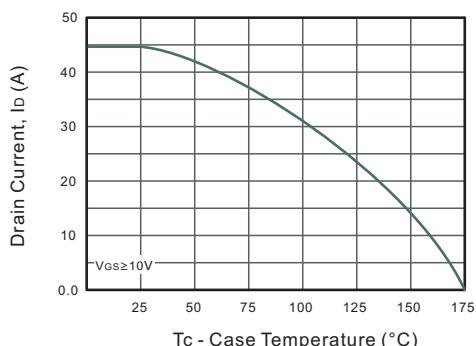


Fig.11 Gate Charge Characteristics

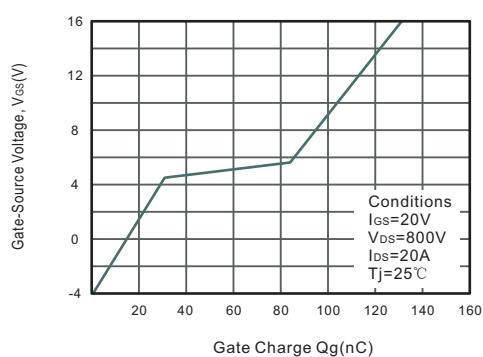


Fig.12 Power Dissipation

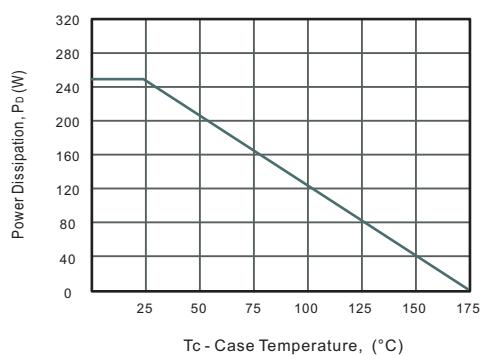
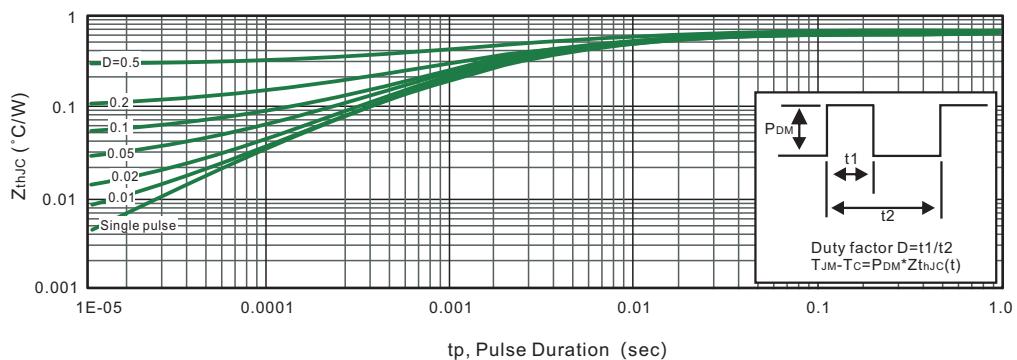


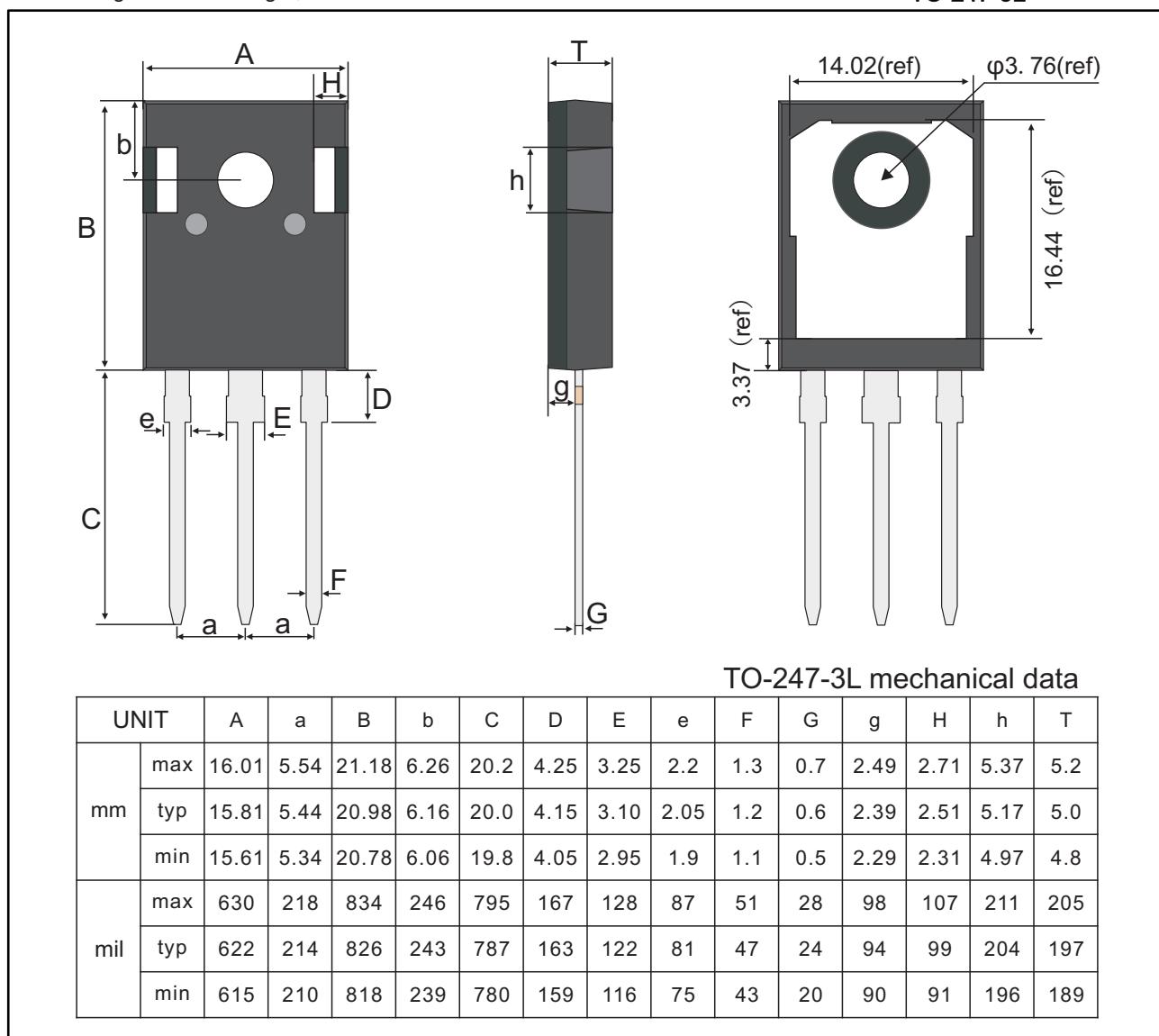
Fig.13 Max. Transient Thermal Impedance





Package Outline
Through Hole Package ; 3 leads

TO-247-3L



Marking

Type number	Marking code
SC060N120WT	SC060N120WT



Important Notice and Disclaimer

Jingdao Microelectronics reserves the right to make changes to this document and its products and specifications at any time without notice.

Customers should obtain and confirm the latest product information and specifications before final purchase or use.

Jingdao Microelectronics makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Jingdao Microelectronics assume any liability for application assistance or customer product design.

Jingdao Microelectronics does not warrant or accept any liability with products which are purchased or used for any unintended or unauthorized application.

No license is granted by implication or otherwise under any intellectual property rights of Jingdao Microelectronics.

Jingdao Microelectronics products are not authorized for use as critical components in life support devices or systems without express written approval of Jingdao Microelectronics.